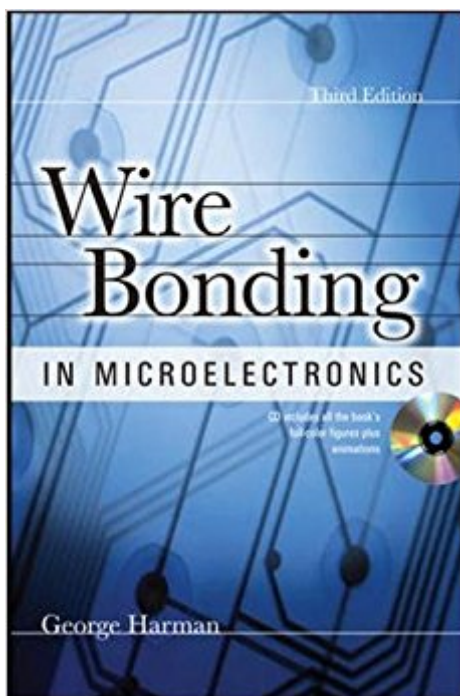


The book was found

WIRE BONDING IN MICROELECTRONICS, 3/E



Synopsis

The Industry Standard Guide to Wire Bonding--Fully Updated The definitive resource on the critical process of connecting semiconductors with their packages. Wire Bonding in Microelectronics, Third Edition, has been thoroughly revised to help you meet the challenges of today's small-scale and fine-pitch microelectronics. This authoritative guide covers every aspect of designing, manufacturing, and evaluating wire bonds engineered with cutting-edge techniques. In addition to gaining a full grasp of bonding technology, you'll learn how to create reliable bonds at exceedingly high yields, test wire bonds, solve common bonding problems, implement molecular cleaning methods, and much more. **COVERAGE INCLUDES:** Ultrasonic bonding systems and technologies, including high-frequency systems Bonding wire metallurgy and characteristics, including copper wire Wire bond testing Gold-aluminum intermetallic compounds and other interface reactions Gold and nickel-based bond pad plating materials and problems Cleaning to improve bondability and reliability Mechanical problems in wire bonding High-yield, fine-pitch, specialized-looping, soft-substrate, and extreme-temperature wire bonds Copper, low-dielectric-constant (Cu/Lo-k) technology and problems Wire bonding process modeling and simulation CD includes all of the book's full-color figures plus animations.

Book Information

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Customer Reviews

George G. Harman is a Fellow of the National Institute of Standards and Technology's Semiconductor Electronics Division.

Wire Bonding in Microelectronics continues to be the definitive resource for wire bonding information.

The book is great! Both in quality of the book and on the content. It was a great help for me, especially on my field of work.

It took a lot longer then I expected to get shipped out but maybe they were out of stock and found one for me. If that is the case then that's awesome. I only paid \$45 including shipping.

I had the first edition of this book which was printed in about 1989. The new edition has been expanded to include many more details on newer technologies such as wire bonding on no traditional surfaces such as immersion gold, and nickel palladium gold.

Good to read. It was helpfull for me.

It's a great book by one of the leading authorities in wirebonding. George Harman knows the material science, reliability, process, and so many other details involved in wirebonding.

This updated edition is a must have for anybody working in the wire bonding industry! Well done!

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